

OT2-SCANGe071-T4

Rev: 15.2

Date	2021.06.28
Language	English
SDS	950612



SUMMARY

Pb-free - Low Silver, latest technology No-Clean, Fine Pitch solder paste - Anti tombstoning - Halide/Halogen free

PASTE	OT2-SCANGe071-T4
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	8

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	9
Pb-free process N2	9
Vapor phase process	8
Shiny joint appearance	6
Cosmetic cleanliness	9
ICCT compatible	9
Conformal coating	8

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

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CLASSIFICATION	
DIN-EN-29454-1: 1994	1.1.3.C
IPC-J-STD-004-A: 2004	ROL0
IPC-J-STD-005: 1995 (Powder)	T4
Particle size	[µm] 20-38

PROPERTIES	
Flux code	OT2
Alloy Code	SCANGe071
Alloy composition	Sn98.3Cu0.7Ag1NiGe
Liquidus	[°C] 225
Solidus	[°C] 217
Recommended peak temp.	[°C] 232-260
Acid number	[mg KOH/g] 139.5
Flux	[% w/w] 12.2
Residues	Colorless
Tackiness Malcom TK1	JIS-Z-3284 [gf] @ 0h 120

TEST REPORTS	
IPC/ANSI-J-STD-005	Compliant
Certificate of Compliance	Website
RoHS Compliant	Available
Application Note	EN/DE
Copper Mirror	IPC-TM-650 2.3.32 Pass
Halides	IPC-TM-650 2.3.33 [Silver Chromate] Pass
Halide	IPC-TM-650 2.3.35.1 [Fluoride by Spot] Pass
Copper Corrosion	IPC-TM-650 2.6.15 Pass
SIR	IPC-TM-650 2.6.3.3 Pass
ECM	IPC-TM-650 2.6.14.1 Pass

PACKAGING AND STORAGE	
Packaging jar	PP [g] 500
Packaging cartridge	HDPE [g] 650
Packaging cartridge	HDPE [g] 1300
Packaging Cassette Pro-Flow	[g] 800
Minimum shelf-life in months	4-10 °C 12